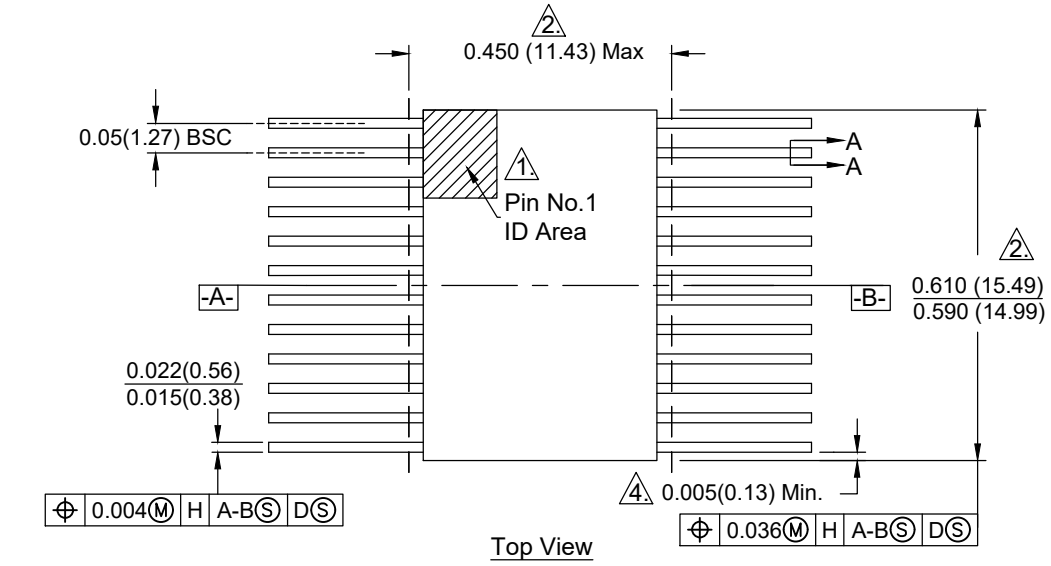
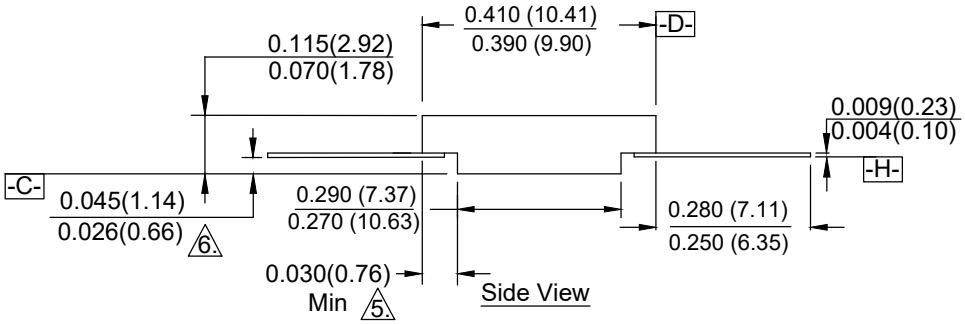
Package Outline Drawing

24 Lead Ceramic Metal Seal Flatpack

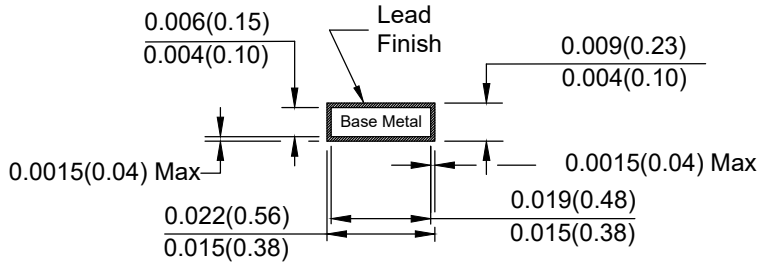
POD No: K24.A, Revision No: 01, Date Created: May12, 2025



Top View



Side View



Section A-A 3.

Notes:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacture's identification shall not be used as a pin one identification mark.
2. This dimension allows for off-center lid, meniscus, and glass overrun.
3. The maximum limits of lead dimensions (SECTION A-A) shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
4. Measure dimension at all four corners.
5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
6. This Dimension shall be measured at the point of exit (beyond the meniscus) of the lead from the body. This dimension's minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
7. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
8. Dimensions: INCH(mm). Controlling dimension: INCH.
9. Meets MIL-STD-1835 CDFP4-F24 (F-6A, Configuration B).

© Renesas Electronics Corporation